

### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Forward Current	I <sub>F(AV)</sub>	1.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	IFSM	35	А

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	PD	1.67	W
Power Dissipation (Note 6)	PD	556	mW
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>0JA</sub>	60	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R <sub>0JA</sub>	180	°C/W
Typical Thermal Resistance Junction to Soldering (Note 7)	R <sub>θ</sub> JS	10	°C/W
Operating Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

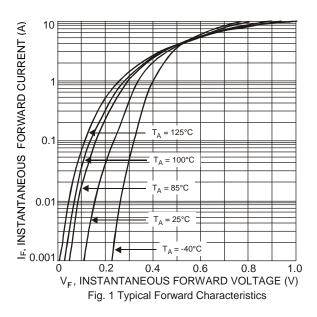
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V <sub>(BR)R</sub>	30	_		V	I <sub>R</sub> = 1.5mA
Forward Voltage (Note 8)	VF		0.25 0.33	 0.37		I <sub>F</sub> = 0.1A I <sub>F</sub> = 0.7A
		_	0.36	0.42		I <sub>F</sub> = 1.0A
Leakage Current (Note 8)	I <sub>R</sub>	_	0.15	1.0	mA	V <sub>R</sub> = 30V, T <sub>A</sub> = +25°C
Total Capacitance	CT		40		pF	V <sub>R</sub> = 10V, f = 1.0MHz

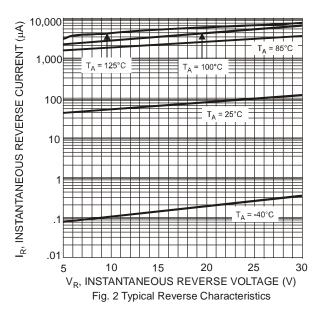
Notes: 5. Part mounted on 50.8mm X 50.8mm GETEK board with 25.4mm X 25.4mm copper pad, 25% anode, 75% cathode.

6. Part mounted on FR-4 board with 1.8mm X 2.5mm cathode and 1.8mm X 1.2mm anode, 1 oz. copper pads.

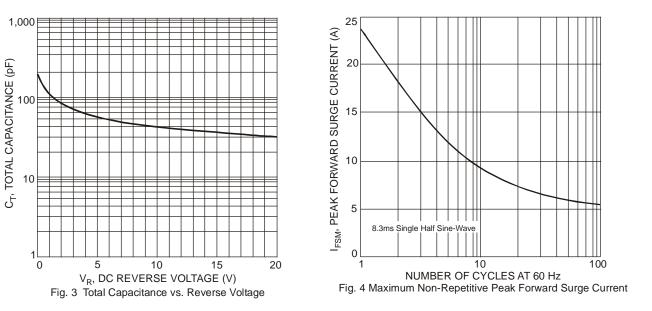
7. Theoretical  $R_{\theta,JS}$  calculated from the top center of the die straight down to the PCB cathode tab solder junction.

8. Short duration pulse test used to minimize self-heating effect.



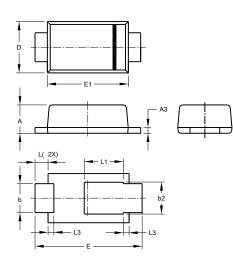






# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



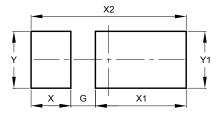
### PowerDI123

PowerDI123				
Dim	Min	Max	Тур	
Α	0.93	1.00	0.98	
A3	0.15	0.25	0.20	
b	0.85	1.25	1.00	
b2	1.025	1.125	1.10	
D	1.63	1.93	1.78	
E	3.50	3.90	3.70	
E1	2.60	3.00	2.80	
L	0.40	0.50	0.45	
L1	1.25	1.40	1.35	
L3	0.125	0.275	0.20	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## PowerDI123



Dimensions	Value (in mm)
G	0.65
Х	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50



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